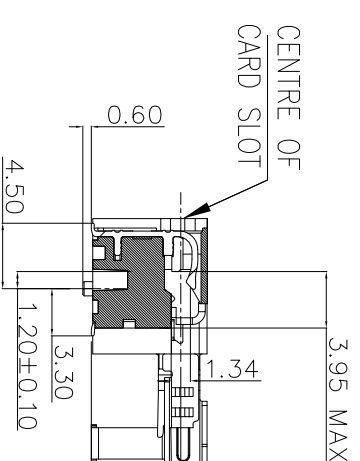
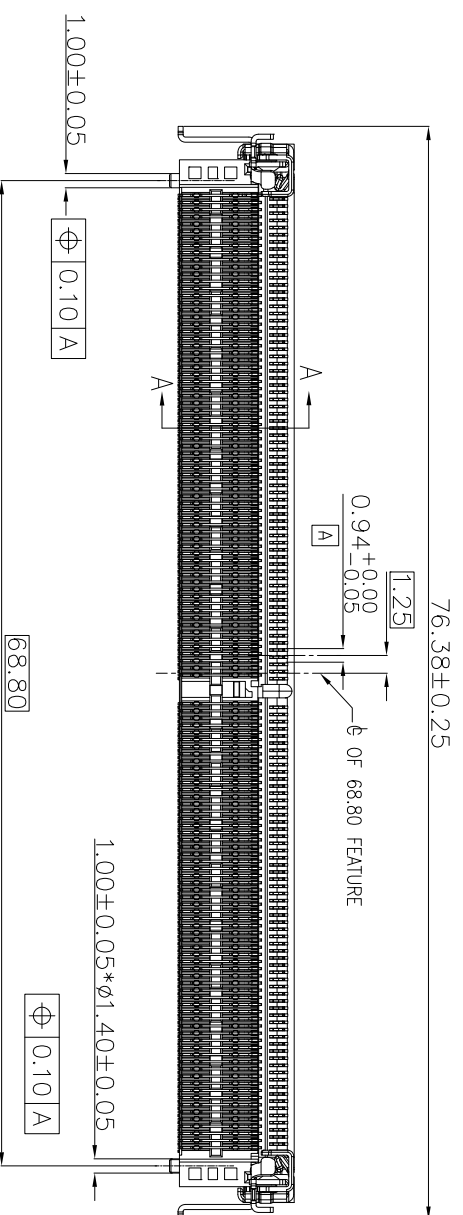


- NOTES:
- 1.FINISH:
 - 1.1 CONTACT:50U" MIN NICKEL UNDERPLATED ALL OVER.
GOLD FALSH PLATING ON SOLDERAIL.
GOLD PLATING (THICKNESS SEE P/N)NO CONTACT AREA.
 - 1.2 SOLDER PEG:
50U"MIN NICKEL UNDERPLATED ALL OVER.
100U"MIN MATTE TIN PLATING ENTIRE OVER.
 - 2.DATE CODE:YYWDLX.
YY:YEAR(20:2020)
MM:MONTH(01:JANUARY)
DD:DAY(1~31)
 - 3.RECOMMENDED STENCIL THICKNESS:0.12mm MIN

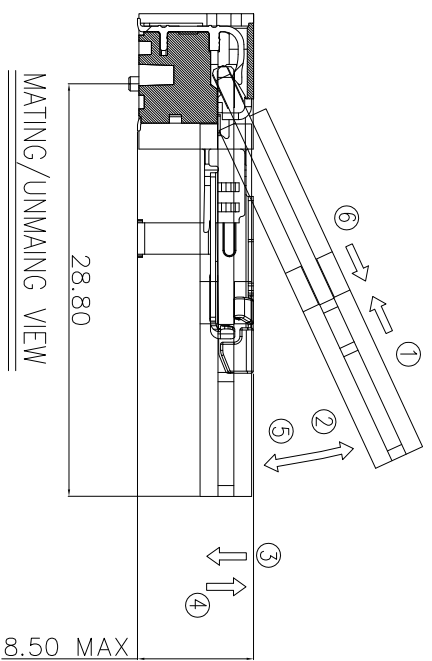
PART.NO.:

DDR005-S5401-**-**

- 08: 1U"
- 09: 3U"
- 10: 5U"
- 11: 10U"
- 12: 15U"
- 13: 30U"



SECTION:A-A
SCALE 2:1



MATING:① INSETTING(25) → ② ROTATING → ③ FIXED
UNMATING:④ INSETTING(25) → ⑤ ROTATING → ⑥ WITHDRAWING

| NO | DESCRIPTION | QTY | MATERIAL | PLATING & COLOR |
|----|-------------|-----|--------------|------------------------------------|
| G | FIXED-B | 1 | SUS304 0.35T | |
| F | FIXED-A | 1 | SUS304 0.35T | Matt Tin plating All Over 120u"Min |
| E | LATCH-B | 1 | SUS304 0.35T | |
| D | LATCH-A | 1 | SUS304 0.35T | Clear |
| C | TERMINAL-B | 131 | C5210 0.15T | Contact area gold plating Solder |
| B | TERMINAL-A | 131 | C5210 0.15T | TAIL G/F Ni 50u"Min Underplate |
| A | HOUSING | 1 | LCP,UL94V-0 | BLACK. |

GENERAL TOLERANCE DWG.NO. DDR005-S5401-**-**

PART.NO. DDR005-S5401-**-**

DRAWN DU 2023-06-06

UNIT mm SCALE ND SCALE

X.±0.50 X.±5° REV. SIZE A4

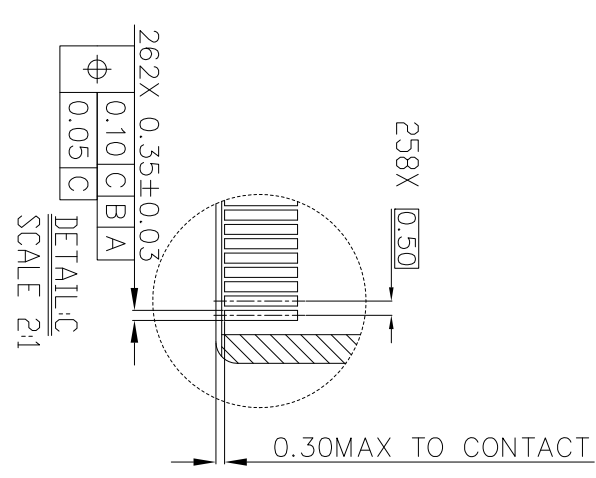
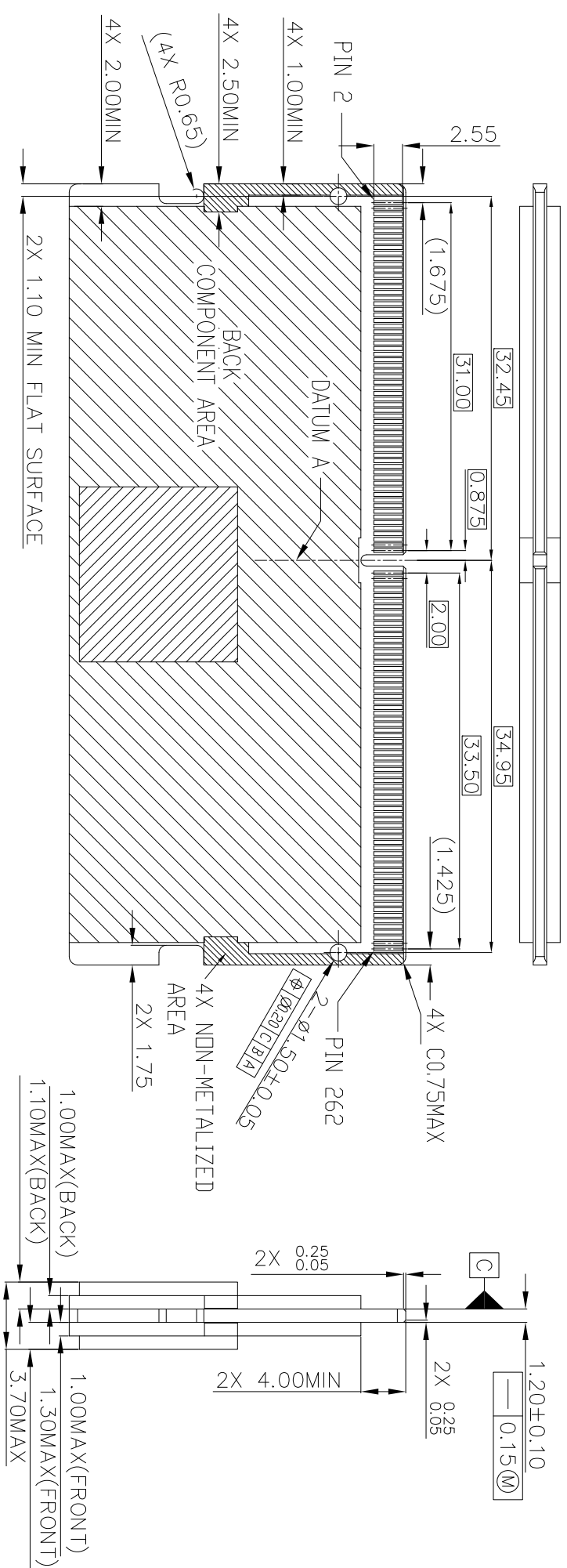
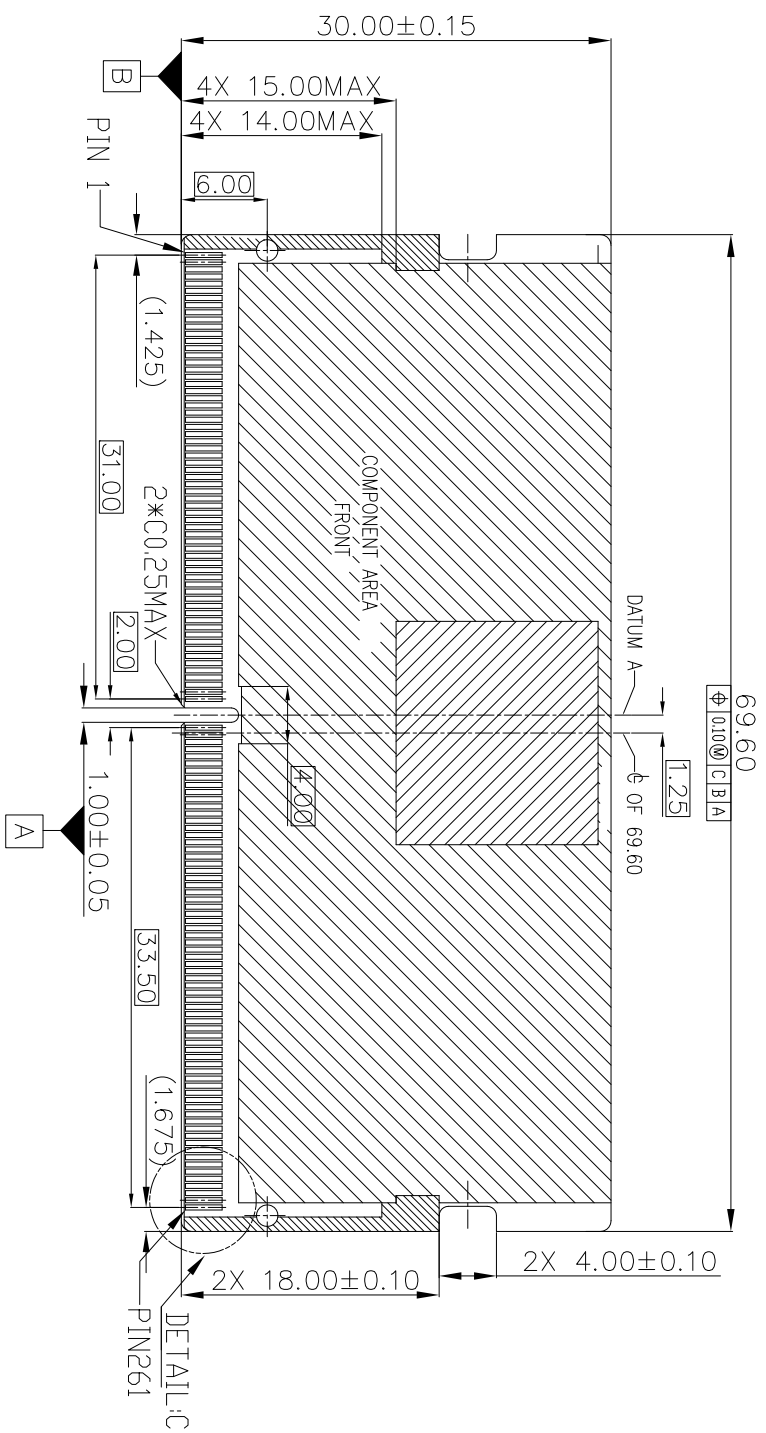
TITLE SHEET

CHECKED APPROVED

DDR5 SO DIMM 262Pin(STD) H8.0 1 OF 4

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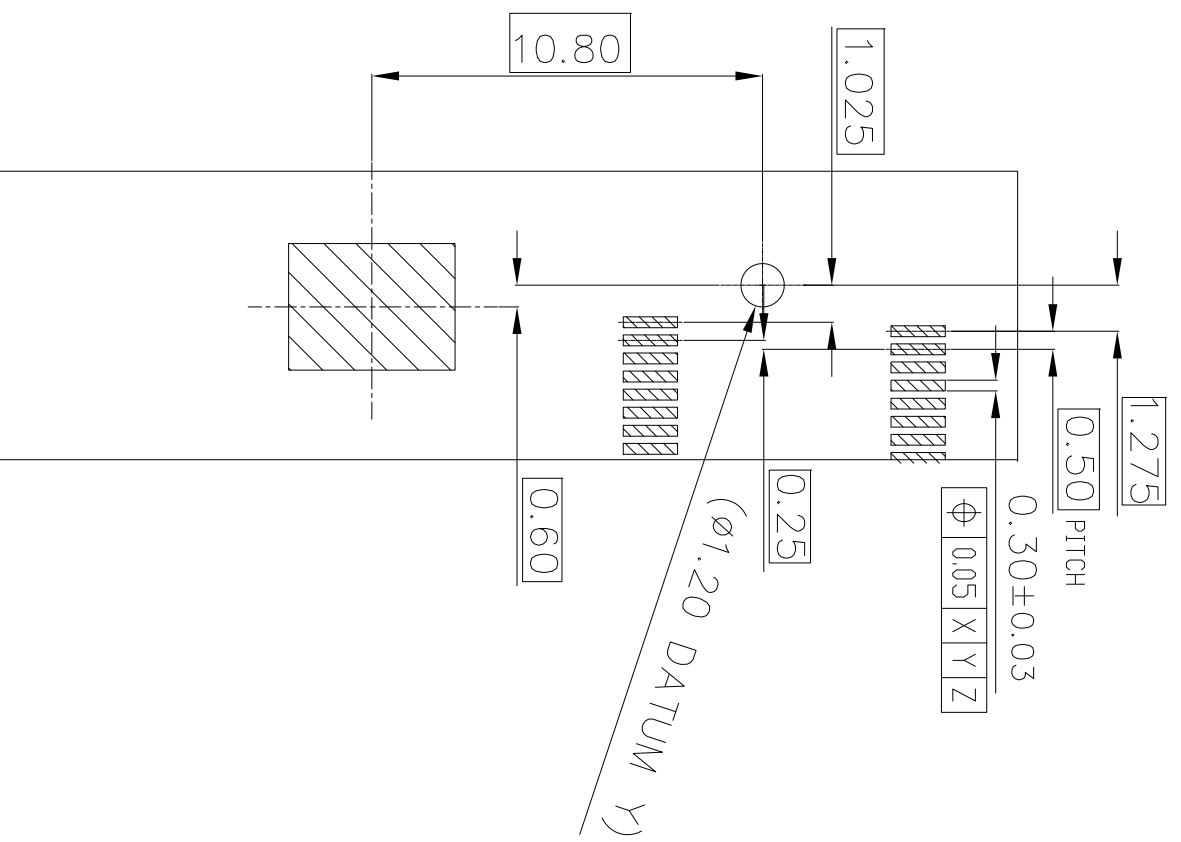
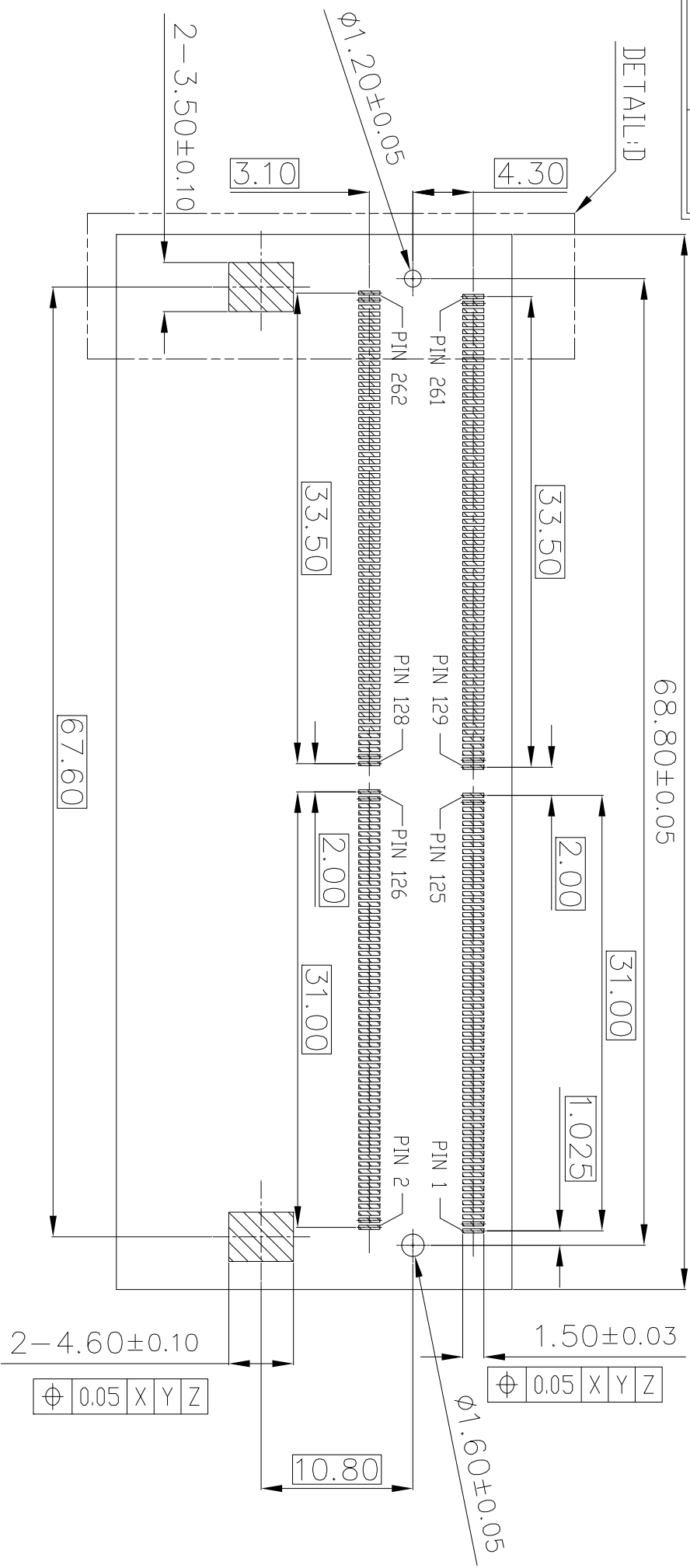
| REV. | ECH. NO. | MODIFY CONTENT |
|------|-----------|------------------------|
| A | | NEW |
| B | N23060601 | CHANGE LATCH AND FIXED |



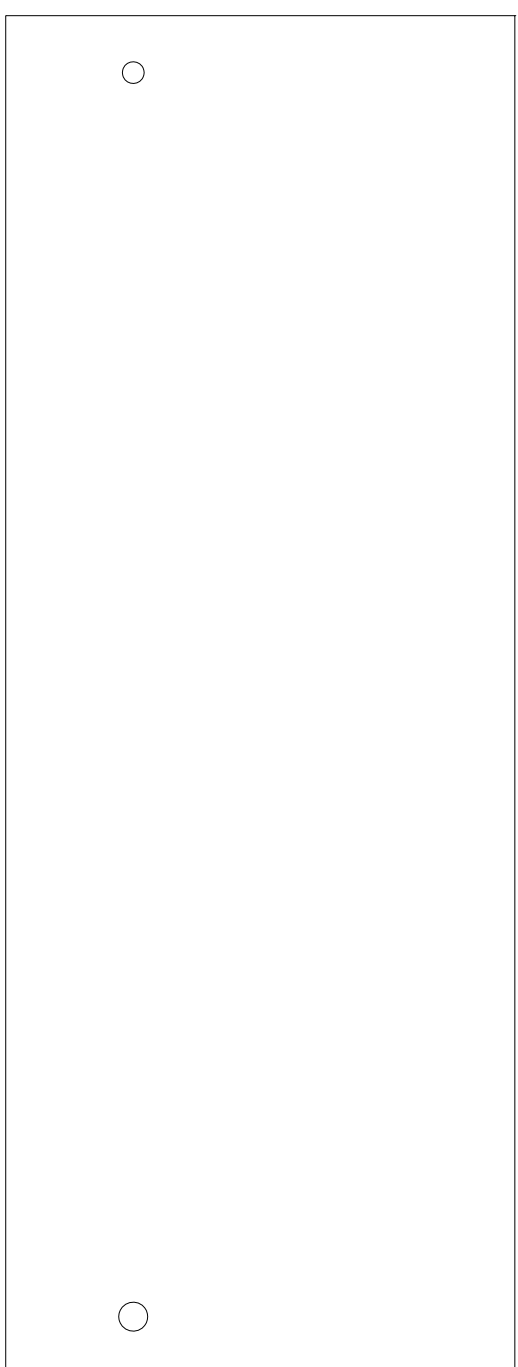
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5-2009.
 2. TOLERANCES ON ALL DIMENSIONS 0.15 UNLESS OTHERWISE SPECIFIED.
 3. ALL DIMENSIONS ARE MM.
 4. RECOMMENDED PLATING FOR CONTACT PADS ARE:
 - 1) VARIATION xxAX: GOLD PLATING 0.76 MICROMETERS MINIMUM OVER 2.00 MICROMETERS MINIMUM NICKEL.
 - 2) VARIATION xxBx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 0.25 MICROMETERS MINIMUM PALLADIUM OVER 2.00 MICROMETERS MINIMUM NICKEL
 - 3) VARIATION xxCx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 2.00 MICROMETERS MINIMUM NICKEL.
- MODULE PLATING RECOMMENDATIONS TESTED PER INDUSTRY STANDARD EIA 364-1000. RELIABILITY TESTING REQUIRES TEST MODULE, CONNECTOR, AND IDENTIFICATION OF TEST CONDITIONS.

| GENERAL | TOLERANCE | DWG. NO. | DDR005-SS401-** | PART. NO. | DDR005-SS401-** | DRAWN | DU | 2023-06-06 | UNIT | mm | SCALE | ND SCALE |
|----------|-----------|----------|-----------------|-----------|-------------------------------|----------|----|------------|------|----|-------|----------|
| X.±0.50 | X.± 5° | REV. | B | TITLE | DDRS 50 DIMM 262Pin(STD) H8.0 | CHECKED | | | | | | |
| X.±0.25 | X.± 2° | SIZE | A4 | SHEET | 2 OF 4 | APPROVED | | | | | | |
| .xx±0.15 | .xx± 1° | | | | | | | | | | | |


| REV. | ECN.NO. | MODIFY CONTENT |
|------|-----------|------------------------|
| A | — | NEW |
| B | N23060601 | CHANGE LATCH AND FIXED |



DETAIL:D
SCALE 2:1



RECOMMEND PCB LAYOUT
THE TOLERANCE UNLESS SPECIFIED IS ±0.05 MM

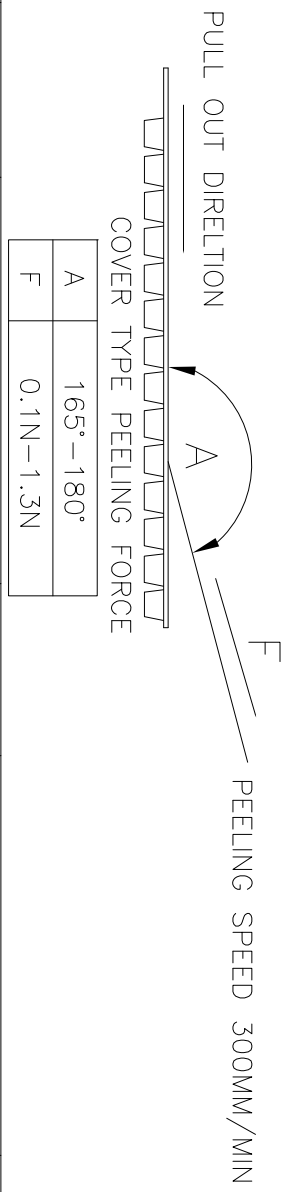
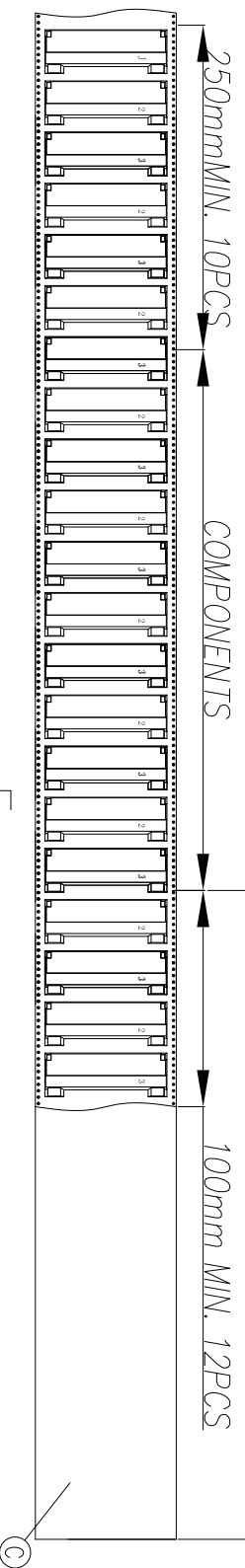
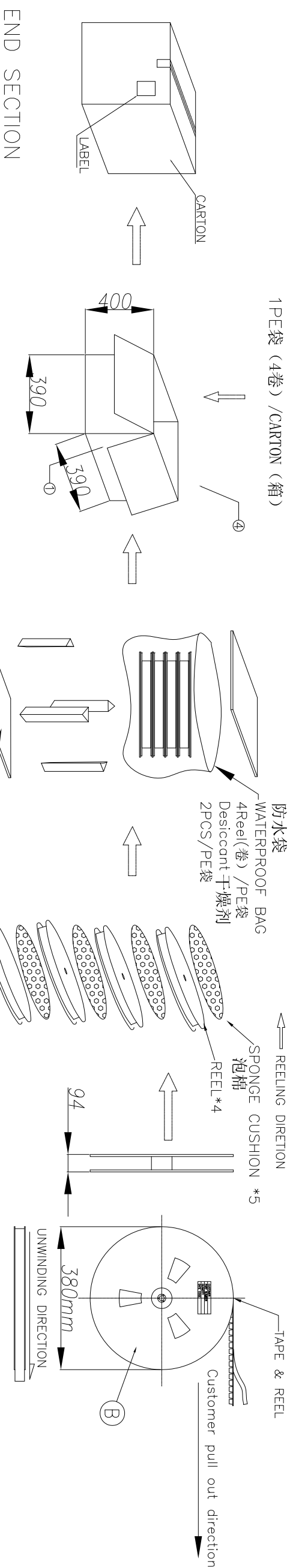
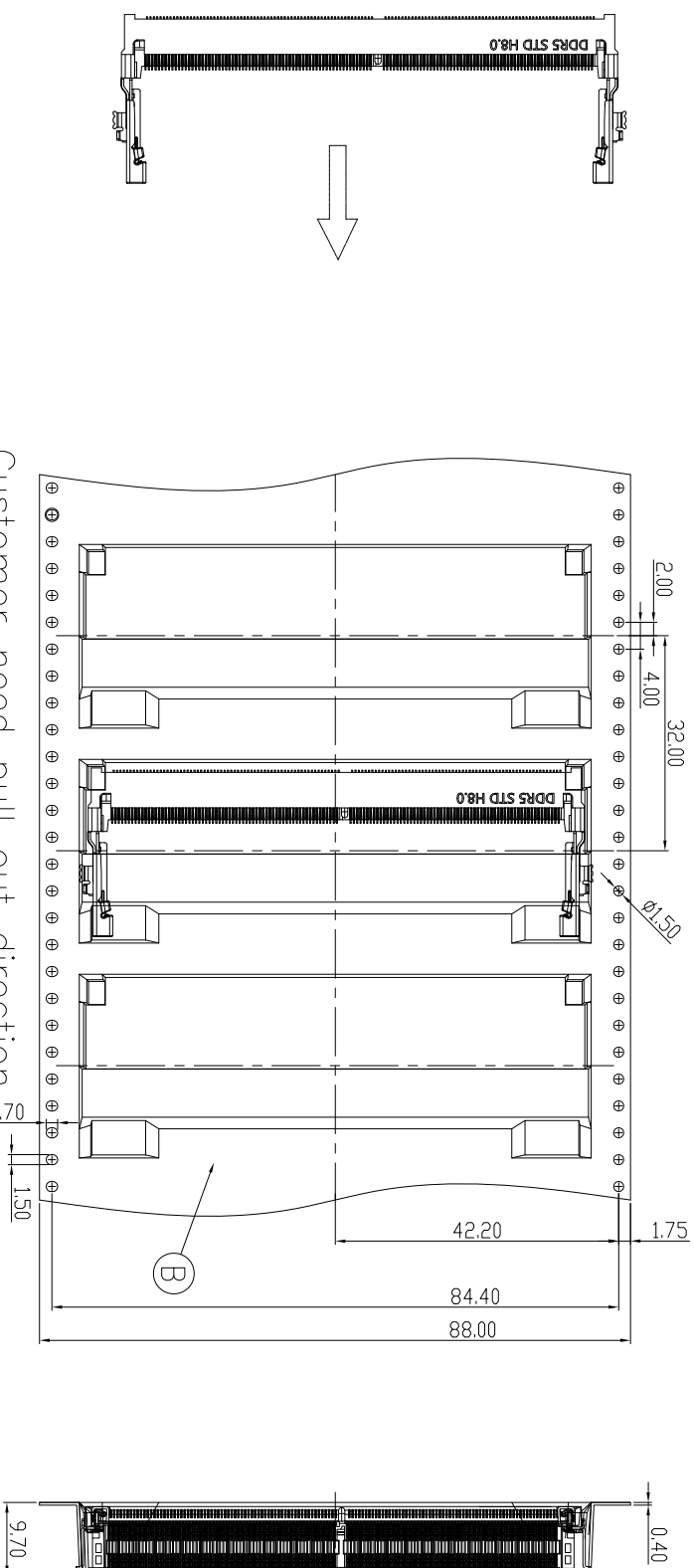
 Solder pad area

| GENERAL | TOLERANCE | DWG.NO. | DDR005-SS401-** | PART.NO. | DDR005-SS401-** | DRAWN | DU | 2023-06-06 |
|----------|-----------|---------|-----------------|----------|-------------------------------|----------|----|------------|
| X.±0.50 | X.°± 5° | REV. | B | TITLE | DDR5 S0 DIMM 262Pin(STD) H8.0 | CHECKED | | |
| .X±0.25 | .X.°± 2° | SIZE | A4 | SHEET | 3 OF 4 | APPROVED | | |
| .XX±0.15 | .XX± 1° | | | | | | | |

UNIT mm SCALE ND SCALE

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| | | |
|------|-----------|------------------------|
| REV. | ECN.NO. | MODIFY CONTENT |
| A | | NEW |
| B | N23060601 | CHANGE LATCH AND FIXED |



NOTES:
 1.Quantity: 280PCS/Reel
 4 Reel/Carton: 1120 PCS/Carton
 2.Each plate needs vacuum packaging, and 2PCS desiccant is placed in the packaging bag

| ITEM | MATERIAL | Q'TY | NOTE |
|------|----------------|------|------|
| ⑤ | WATERPROOF BAG | 1 | |
| ④ | SUPPORT BRACE | 4 | |
| ③ | REEL ASS'Y | 4 | |
| ② | CARRIER TAPE | 4 | |
| ① | CARTON | 1 | |

| | | | | | | | | | | | |
|----------|-----------|---------|-----------------|----------|-------------------------------|----------|---------------|------|----|-------|----------|
| GENERAL | TOLERANCE | DWG.NO. | DDR005-SS401-** | PART.NO. | DDR005-SS401-** | DRAWN | DU 2023-06-06 | UNIT | mm | SCALE | ND SCALE |
| X.±0.50 | X.±5° | REV. | | TITLE | DDR5 SO DIMM 262Pin(STD) H8.0 | CHECKED | | | | | |
| .X±0.25 | .X±2° | SIZE | A4 | SHEET | 4 DF 4 | APPROVED | | | | | |
| .XX±0.15 | .XX±1° | | | | | | | | | | |

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